



Product End-of-Life Disassembly Instructions

Product Category: Personal Computers

Marketing Name / Model
[List multiple models if applicable.]

Compaq dx1000 Microtower PC

Name / Model #2

Name / Model #3

Name / Model #4

Name / Model #5

Purpose: The document is intended for use by end-of-life recyclers or treatment facilities. It provides the basic instructions for the disassembly of HP products to remove components and materials requiring selective treatment, as defined by EU directive 2002/96/EC, Waste Electrical and Electronic Equipment (WEEE).

1.0 Items Requiring Selective Treatment

1.1 Items listed below are classified as requiring selective treatment.

1.2 Enter the quantity of items contained within the product which require selective treatment in the right column, as applicable.

Item Description	Notes	Quantity of items included in product
Printed Circuit Boards (PCB) or Printed Circuit Assemblies (PCA)	With a surface greater than 10 sq cm	2
Batteries	All types including standard alkaline and lithium coin or button style batteries	1
Mercury-containing components	For example, mercury in lamps, display backlights, scanner lamps, switches, batteries	0
Liquid Crystal Displays (LCD) with a surface greater than 100 sq cm	Includes background illuminated displays with gas discharge lamps	0
Cathode Ray Tubes (CRT)		0
Capacitors / condensers (Containing PCB/PCT)		0
Electrolytic Capacitors / Condensers measuring greater than 2.5 cm in diameter or height	The QTY may vary from different PSU Models	2
External electrical cables and cords		0
Gas Discharge Lamps		0
Plastics containing Brominated Flame Retardants weighing > 25 grams (not including PCBs or PCAs already listed as a separate item above)	system fan, cooler	2
Components and parts containing toner and ink, including liquids, semi-liquids (gel/paste) and toner	Include the cartridges, print heads, tubes, vent chambers, and service stations.	0
Components and waste containing asbestos		0

Components, parts and materials containing refractory ceramic fibers		0
Components, parts and materials containing radioactive substances		0

1.3 Markings for plastic parts greater than 25 grams

Plastic Part Name	Plastic Part Description	Weight (grams)	ISO 11469:2000 Plastic Part Mark	Optional: Photo
Alamo Main Bezel	Main front bezel piece	150	>ABS<	
Alamo Anna Bezel Frame	Front bezel frame	194	>ABS<	
System Fan Frame	Fan Frame	47	>PBT-GF30-FR(17)<	
CPU Heatsink Fan Frame	Fan Frame	35	>PBT-GF30-FR(17)<	

2.0 Tools Required

List the type and size of the tools that would typically be used to disassemble the product to a point where components and materials requiring selective treatment can be removed.

Tool Description	Tool Size (if applicable)
Description #1 Trox screw driver	T10
Description #2 Soldering Iron	
Description #3	
Description #4	
Description #5	

3.0 Product Disassembly Process

3.1 List the basic steps that should typically be followed to remove components and materials requiring selective treatment:

1. Remove cover from the unit
2. Remove all the cables from PCA
3. Remove PCI & PCI-E card from the PCA
4. Remove HDD from the system Remove ODD from PCA
5. Take off Front Panel
6. Take off ODD
7. Take off Cooler
8. Take off CMOS battery
9. Take off PS from the Unit
10. Cut off wire tie
11. Open PSU
12. Use screw driver to separate the small PCA from the main board
13. Electrolytic Capacitors location

3.2 Optional Graphic. If the disassembly process is complex, insert a graphic illustration below to identify the items contained in the product that require selective treatment (with descriptions and arrows identifying locations).



1 Remove cover from the unit

Rotate screw to open the cover



2 Remove all the cables from PCA

Press the button to pull power cords off

Pull the other cords off PCA



3 remove PCI & PCI-E card from the PCA

Use screw driver to take off the screw as shown in the photo



3 Take PCI & PCI-E cards off the PCA

Use one hand to push the white plastic use the other hand to pull off the card






4 Remove HDD from the system

Rotate the screw driver to take off the HDD holder



5 Take off Front Panel

Pull the button up and then take off the front panel

	<p>6 Take off ODD Use one hand to pull the steel up , and the same time take off ODD use the other hand</p>
	<p>7 Take off Cooler</p> <p>7.1 Press the steel button to loose Cooler fan</p>
	<p>7 Take off Cooler</p> <p>7.2 Rotate screw driver to loose screw and then take the cooler off PCA</p>



8 Take off CMOS battery
Pull the battery holder as shown in the photo, and then the battery will be off the PCA



9 Take off PS from the Unit
Use screw driver to loose screws and then take the PS off the Unit



10 Cut off wire tie



11 open PSU



12 Use screw driver to separate the small PCA from the main board



13 Remove Electrolytic Capacitors
13.1 Electrolytic Capacitors



13 Remove Electrolytic Capacitors
13.2 Use the Soldering Iron to heat the solder of Electrolytic Capacitors and then remove it

